

# NUF2450

## 2 Line EMI Filter with ESD Protection

This device is a 2 line EMI filter array for audio applications. Greater than -30 dB attenuation is obtained at frequencies from 800 MHz to 5.0 GHz. The NUF2450MU has a cut-off frequency of 20 MHz and minimal line resistance, making it ideal for applications requiring low bandpass attenuation. This UDFN package is specifically designed to enhance EMI filtering for low-profile or slim design electronics especially where space and height is a premium. It also offers ESD protection—clamping transients from static discharges. ESD protection is provided across all capacitors.

### Features

- EMI Filtering and ESD Protection
- Integration of 10 Discrete Components
- Compliance with IEC61000-4-2 (Level 4)  
20 kV (Contact)
- UDFN Package, 1.2 x 1.8 mm
- Moisture Sensitivity Level 1
- ESD Ratings: Machine Model = C  
Human Body Model = 3B
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### Benefits

- Reduces EMI/RFI Emissions on Audio Lines
- Low Profile Package; Typical Height of 0.5 mm
- Design-Friendly and Easy-to-Use Pin Configurations, Particularly for Portable Electronics
- Integrated Solution Offers Cost and Space Savings in UDFN Package
- Reduces Parasitic Inductances Which Offer a More “Ideal” Low Pass Filter Response
- Integrated Solution Improves System Reliability
- Excellent ESD Performance with Large GND Pad

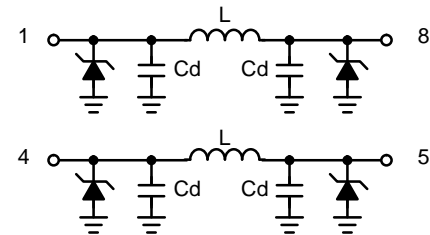
### Applications

- Headsets, MP3 Players, and PDAs
- Portable DVDs
- Hands-Free Interface



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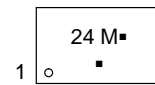


(Top View)



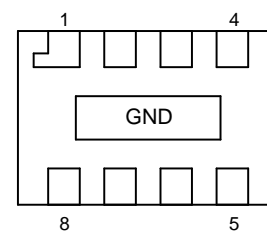
UDFN8  
CASE 517AD

### MARKING DIAGRAM



24 = Specific Device Code  
M = Month Code  
▪ = Pb-Free Package  
(Note: Microdot may be in either location)

### PIN CONNECTIONS



(Bottom View)

### ORDERING INFORMATION

| Device       | Package            | Shipping†          |
|--------------|--------------------|--------------------|
| NUF2450MUT2G | UDFN8<br>(Pb-Free) | 3000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# NUF2450

## MAXIMUM RATINGS

| Parameter                                                                            | Symbol    | Value      | Unit |
|--------------------------------------------------------------------------------------|-----------|------------|------|
| ESD Discharge IEC61000-4-2<br>Contact Discharge<br>Machine Model<br>Human Body Model | $V_{PP}$  | 20         | kV   |
|                                                                                      |           | 1.6        |      |
|                                                                                      |           | 16         |      |
| Operating Temperature Range                                                          | $T_{OP}$  | -40 to 85  | °C   |
| Storage Temperature Range                                                            | $T_{STG}$ | -55 to 150 | °C   |
| Maximum Lead Temperature for Soldering Purposes (1.8 in from case for 10 s)          | $T_L$     | 260        | °C   |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

| Parameter                       | Symbol     | Test Conditions                                         | Min | Typ | Max | Unit     |
|---------------------------------|------------|---------------------------------------------------------|-----|-----|-----|----------|
| Maximum Reverse Working Voltage | $V_{RWM}$  |                                                         | -   | -   | 5.0 | V        |
| Breakdown Voltage               | $V_{BR}$   | $I_R = 1.0 \text{ mA}$                                  | 6.0 | 7.0 | 8.0 | V        |
| Leakage Current                 | $I_R$      | $V_{RWM} = 3.3 \text{ V}$                               | -   | -   | 100 | nA       |
| Inductance                      | L          |                                                         | -   | 2.3 | -   | nH       |
| Series Resistance               | $R_S$      |                                                         | 0.9 | 1.3 | 1.7 | $\Omega$ |
| Capacitance (Note 1)            | $C_{line}$ | $V_R = 0 \text{ V}, f = 1.0 \text{ MHz}$                | 190 | 240 | 290 | pF       |
| Cut-Off Frequency (Note 2)      | $f_{3dB}$  | Above this frequency,<br>Appreciable Attenuation Occurs | -   | 20  | -   | MHz      |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Measured at  $25^\circ\text{C}$ .
2.  $50 \Omega$  source and  $50 \Omega$  load termination.

## TYPICAL CHARACTERISTICS

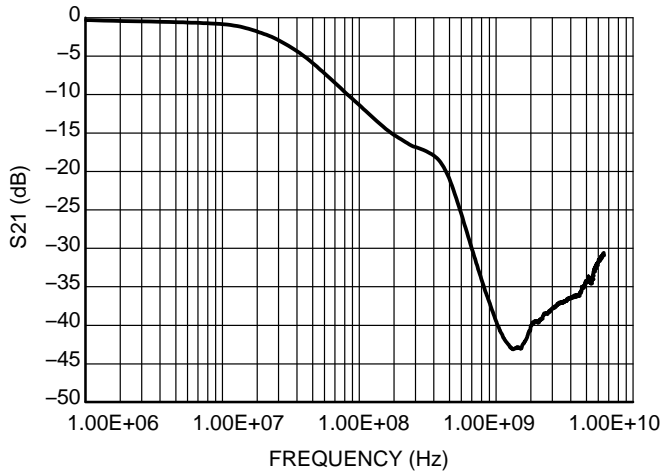


Figure 1. Typical Insertion Loss Characteristics (S21 Measurement)

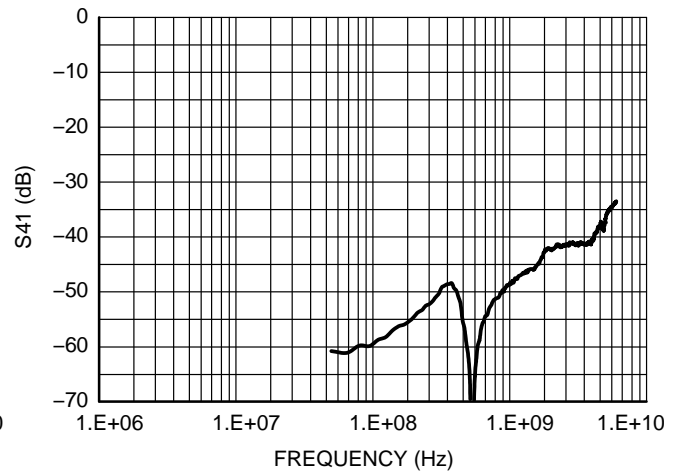


Figure 2. Analog Crosstalk Curve (S41 Measurement)

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

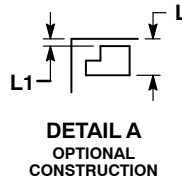
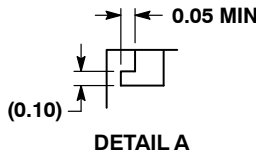
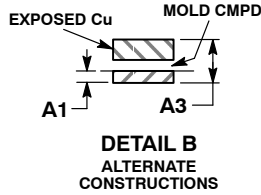
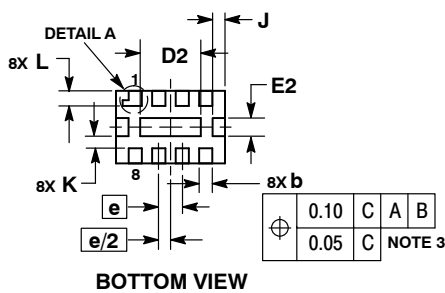
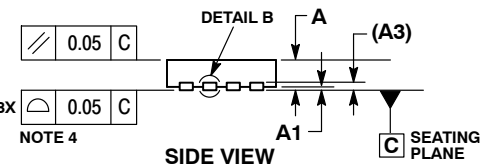
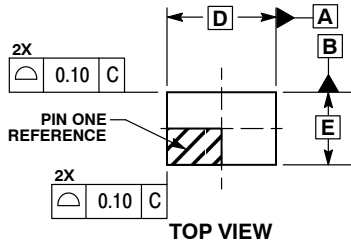
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SCALE 4:1

### UDFN8 1.8x1.2, 0.4P CASE 517AD ISSUE D

DATE 23 OCT 2012

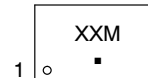


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

| MILLIMETERS |      |      |
|-------------|------|------|
| DIM         | MIN  | MAX  |
| A           | 0.45 | 0.55 |
| A1          | 0.00 | 0.05 |
| A3          | 0.13 | REF  |
| b           | 0.15 | 0.25 |
| D           | 1.80 | BSC  |
| E           | 1.20 | BSC  |
| e           | 0.40 | BSC  |
| D2          | 0.90 | 1.10 |
| E2          | 0.20 | 0.30 |
| J           | 0.19 | REF  |
| K           | 0.20 | TYP  |
| L           | 0.20 | 0.30 |
| L1          | ---  | 0.10 |

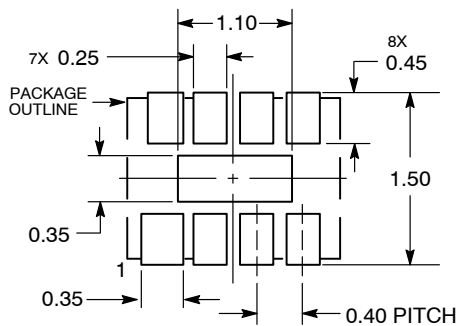
#### GENERIC MARKING DIAGRAM\*



- XX = Specific Device Code
- M = Date Code
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

#### SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

|                         |                            |                                                                                                                                                                                  |
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